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Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	1.6mm +/-0.20mm
B	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	Waffle, Tray
Packaging Quantity	50

General Information	
Series	SMD Indust COG HT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Gold
Marking	No
AEC-Q200	No
Component Weight	36 mg
Miscellaneous	Moisture Sensitive Packaging. Gold (Au) 30 - 70 micro inches.
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.1 uF
Measurement Condition	1kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms

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